

## Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Fast reverse recovery
- 4) Easy to parallel
- 5) Simple to drive
- 6) Pb-free lead plating ; RoHS compliant

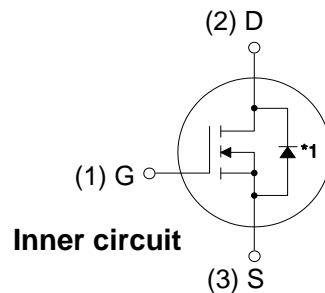
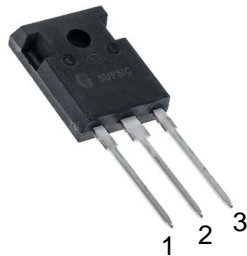
Parameter	Rating	Units
$V_{DS}$	<b>650</b>	V
$I_D$ @ 25°C	<b>122</b>	A
$R_{DS(on)}$	<b>15</b>	m $\Omega$



## Applications

- Solar inverters
- DC/DC converters
- Switch mode power supplies
- Induction heating

TO-247-3  
Package



- (1) Gate  
(2) Drain  
(3) Source

\*1 Body Diode

Maximum Ratings ( $T_c=25^\circ\text{C}$ , unless otherwise specified)

Symbol	Parameter	Value	Unit	Note
$V_{DSmax}$	Drain - Source Voltage	650	V	
$V_{GSmax}$	Gate - Source voltage	-8/+19	V	
$I_D$	Continuous Drain Current, $V_{GS} = 15\text{ V}$ , $T_c = 25^\circ\text{C}$	122	A	
	Continuous Drain Current, $V_{GS} = 15\text{ V}$ , $T_c = 100^\circ\text{C}$	98		
$I_{D(pulse)}$	Pulsed Drain Current, Pulse width $t_p$ limited by $T_{jmax}$	430	A	
$P_D$	Power Dissipation, $T_c=25^\circ\text{C}$ , $T_j = 175^\circ\text{C}$	420	W	
$T_j, T_{stg}$	Operating Junction and Storage Temperature	-40 to +175	$^\circ\text{C}$	
$T_L$	Solder Temperature, 1.6mm (0.063") from case for 10s	260	$^\circ\text{C}$	
$M_d$	Mounting Torque, (M3 or 6-32 screw)	1	Nm	
		8.8	lbf-in	

Note (1): Recommended turn off / turn on gate voltage  $V_{GS} = -4\text{V} \dots 0\text{V} / +15\text{V}$

Note (2): Package limited to 120 A

Electrical Characteristics ( $T_c = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{\text{BRIDSS}}$	Drain-Source Breakdown Voltage	650			V	$V_{\text{GS}} = 0\text{ V}, I_{\text{D}} = 100\text{ }\mu\text{A}$	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	1.8	2.3	3.6	V	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = 15.5\text{ mA}$	
			1.9		V	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = 15.5\text{ mA}, T_{\text{J}} = 175^\circ\text{C}$	
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current		1	50	$\mu\text{A}$	$V_{\text{DS}} = 650\text{ V}, V_{\text{GS}} = 0\text{ V}$	
$I_{\text{GSS}}$	Gate-Source Leakage Current		10	255	nA	$V_{\text{GS}} = 15\text{ V}, V_{\text{DS}} = 0\text{ V}$	
$R_{\text{DS(on)}}$	Drain-Source On-State Resistance	10.5	15	21	m $\Omega$	$V_{\text{GS}} = 15\text{ V}, I_{\text{D}} = 55.8\text{ A}$	
			20			$V_{\text{GS}} = 15\text{ V}, I_{\text{D}} = 55.8\text{ A}, T_{\text{J}} = 175^\circ\text{C}$	
$g_{\text{fs}}$	Transconductance		42		S	$V_{\text{DS}} = 20\text{ V}, I_{\text{DS}} = 55.8\text{ A}$	
			40			$V_{\text{DS}} = 20\text{ V}, I_{\text{DS}} = 55.8\text{ A}, T_{\text{J}} = 175^\circ\text{C}$	
$C_{\text{iss}}$	Input Capacitance		4960		pF	$V_{\text{GS}} = 0\text{ V}, V_{\text{DS}} = 400\text{ V}$ $f = 100\text{ KHz}$ $V_{\text{AC}} = 25\text{ mV}$	
$C_{\text{oss}}$	Output Capacitance		290				
$C_{\text{rss}}$	Reverse Transfer Capacitance		31				
$C_{\text{ol(er)}}$	Effective Output Capacitance (Energy Related)		353				
$C_{\text{ol(tr)}}$	Effective Output Capacitance (Time Related)		516				
$E_{\text{oss}}$	$C_{\text{oss}}$ Stored Energy		29		$\mu\text{J}$		
$E_{\text{ON}}$	Turn-On Switching Energy (Body Diode)		1500		$\mu\text{J}$	$V_{\text{DS}} = 400\text{ V}, V_{\text{GS}} = -4\text{ V}/15\text{ V}, I_{\text{D}} = 55.8\text{ A},$ $R_{\text{G(ext)}} = 5\text{ }\Omega, L = 57.6\text{ }\mu\text{H}, T_{\text{J}} = 175^\circ\text{C}$ FWD = Internal Body Diode of MOSFET	
$E_{\text{OFF}}$	Turn Off Switching Energy (Body Diode)		710				
$E_{\text{ON}}$	Turn-On Switching Energy (External Diode)		1200		$\mu\text{J}$	$V_{\text{DS}} = 400\text{ V}, V_{\text{GS}} = -4\text{ V}/15\text{ V}, I_{\text{D}} = 55.8\text{ A},$ $R_{\text{G(ext)}} = 5\text{ }\Omega, L = 57.6\text{ }\mu\text{H}, T_{\text{J}} = 175^\circ\text{C}$ FWD = External SiC DIODE	
$E_{\text{OFF}}$	Turn Off Switching Energy (External Diode)		1000				
$t_{\text{d(on)}}$	Turn-On Delay Time		22		ns	$V_{\text{DD}} = 400\text{ V}, V_{\text{GS}} = -4\text{ V}/15\text{ V}$ $I_{\text{D}} = 55.8\text{ A}, R_{\text{G(ext)}} = 5\text{ }\Omega, L = 57.6\text{ }\mu\text{H}$ Timing relative to $V_{\text{DS}}$ Inductive load	
$t_{\text{r}}$	Rise Time		128				
$t_{\text{d(off)}}$	Turn-Off Delay Time		60				
$t_{\text{f}}$	Fall Time		25				
$R_{\text{G(int)}}$	Internal Gate Resistance		1.5		$\Omega$	$f = 1\text{ MHz}, V_{\text{AC}} = 25\text{ mV}$	
$Q_{\text{gs}}$	Gate to Source Charge		54		nC	$V_{\text{DS}} = 400\text{ V}, V_{\text{GS}} = -4\text{ V}/15\text{ V}$ $I_{\text{D}} = 55.8\text{ A}$ Per IEC60747-8-4 pg 21	
$Q_{\text{gd}}$	Gate to Drain Charge		62				
$Q_{\text{g}}$	Total Gate Charge		190				

Note (3):  $C_{\text{ol(er)}}$ , a lumped capacitance that gives same stored energy as  $C_{\text{oss}}$  while  $V_{\text{ds}}$  is rising from 0 to 400V  
 $C_{\text{ol(tr)}}$ , a lumped capacitance that gives same charging time as  $C_{\text{oss}}$  while  $V_{\text{ds}}$  is rising from 0 to 400V



### Reverse Diode Characteristics ( $T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$V_{SD}$	Diode Forward Voltage	4.7		V	$V_{GS} = -4\text{ V}, I_{SD} = 27.9\text{ A}, T_J = 25^\circ\text{C}$	
		4.2		V	$V_{GS} = -4\text{ V}, I_{SD} = 27.9\text{ A}, T_J = 175^\circ\text{C}$	
$I_S$	Continuous Diode Forward Current		80	A	$V_{GS} = -4\text{ V}, T_c = 25^\circ\text{C}$	
$I_{S, \text{pulse}}$	Diode pulse Current		420	A	$V_{GS} = -4\text{ V}$ , pulse width $t_p$ limited by $T_{Jmax}$	
$t_{rr}$	Reverse Recovery time	85		ns	$V_{GS} = -4\text{ V}, I_{SD} = 55.8\text{ A}, V_R = 400\text{ V}$ $\text{dif}/\text{dt} = 1500\text{ A}/\mu\text{s}, T_J = 175^\circ\text{C}$	
$Q_{rr}$	Reverse Recovery Charge	670		nC		
$I_{rrm}$	Peak Reverse Recovery Current	17		A		
$t_{rr}$	Reverse Recovery time	74		ns	$V_{GS} = -4\text{ V}, I_{SD} = 55.8\text{ A}, V_R = 400\text{ V}$ $\text{dif}/\text{dt} = 1000\text{ A}/\mu\text{s}, T_J = 175^\circ\text{C}$	
$Q_{rr}$	Reverse Recovery Charge	580		nC		
$I_{rrm}$	Peak Reverse Recovery Current	14		A		

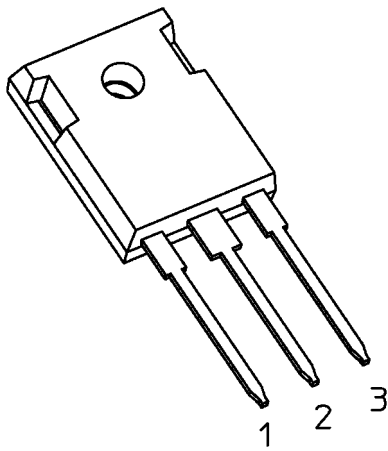
### Thermal Characteristics

Symbol	Parameter	Typ.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.35	$^\circ\text{C}/\text{W}$		
$R_{\theta JA}$	Thermal Resistance From Junction to Ambient	40			

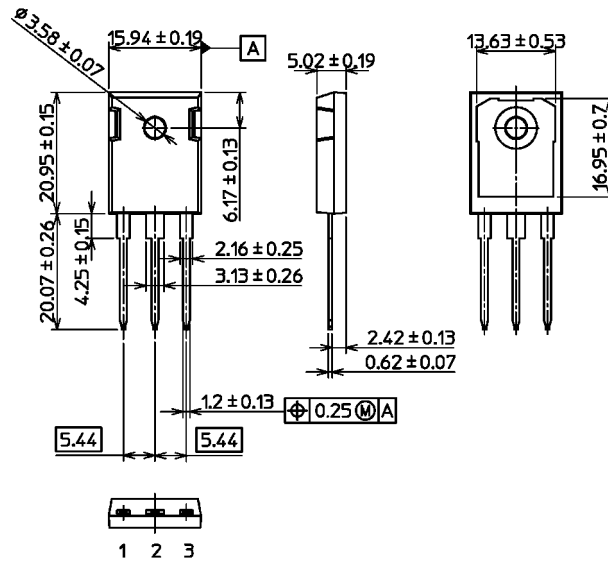


### Package Dimensions

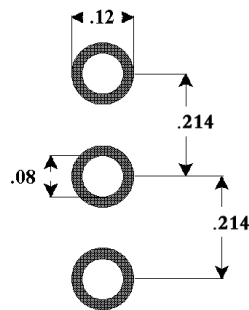
Unit: mm



TO-247-3



### Recommended Solder Pad Layout



TO-247-3